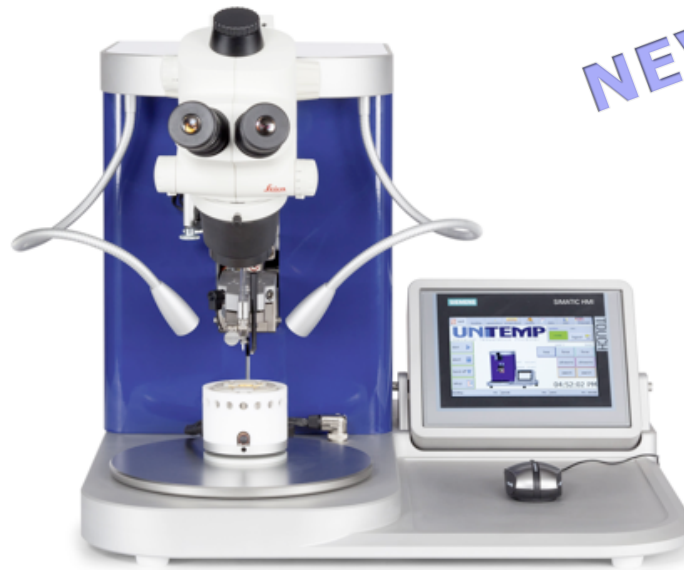


## Model WB200-Pack

### THERMO-SONIC WIRE BONDER

**NEW !!**



**NEW !!**

**DUAL PROCESS DEVICE**  
**WEDGE-WEDGE & BALL-WEDGE**  
**XYZ MOTORIZED AXIS**

Perfect for application as laboratory or prototyping and small series production.

The next generation WB-200 series offers enhanced functionality into a robust and reliable mechanical concept.

In addition to the standard features such as 62KHz transducer, multi-height bonding capabilities, mouse-controlled X-Y motorized Table etc..., the device also has the ability to connect a camera as well as a tool heater. WB200-Pack is suitable for 17 $\mu$ m up to 50 $\mu$ m - Au, Al & Cu wire. Au Stud Bump program included in standard.

Specifications	
MODEL:	JFP WB100 Series
SYSTEM:	Tabletop machine Wedge, Ball and Stud Bump application 17µm to 50µm Au wire Digital control with touch screen panel 90 degrees deep-access bondhead Motorized Z bondhead - 40mm Motorized X&Y table - 50mmx50mm Heater stage Electronic Flame off Missing ball detection Motorized wire clamp Motorized wire spool (2")
Bondhead	Motorized Z Resolution 1µm Wire bond tool, 1/8 Minimum force: 12gr Transducer: WPT140 - 185mm long 2" motorized wire spool
Ultrasonic system	PLL control 0-5 watt 62 KHz Transducer
Parameters	Digital programming Mouse motion drive Touch screen interface - 7" Simatic US Power I & II programmable Force I & II programmable 5 to 100cN Loop height, length & shape programmable Direct or revers loop programmable Bond search height programmable Automatic bond height detection Tail length programmable Wire termination: clamp tear or table tear Temperature programmable Tool heater programmable
Optical & lighting	Std binocular SZ-6 Light: double arm fiber
Workholder	Temperature max 250C Heat controller +/- 1c Adjustable height 12mm travel Rotation upon workholder type
Utilities	100Vac to 230Vac / max 5A Vacuum: 70% 680x640x490mm 45Kgr
OPTIONS	Vertical camera & optics - Video tool offset programmable High optical mag. Digital crossHair Monitor 17"